

RELIABILITY REPORT
FOR
MAX695MJE
PLASTIC ENCAPSULATED DEVICES

October 28, 2014

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Conclusion

The MAX695MJE successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX690 Family of supervisory circuits reduce the complexity and number of components required for power supply monitoring and battery control functions in microprocessor systems. These include p..P reset and backup-battery switchover, watchdog timer, CMOS RAM write protection, and power-failure warning. The MAX690 Family significantly improves system reliability and accuracy compared to that obtainable with separate ICs or discrete components.

The MAX690, MAX692 and MAX694 are supplied in 8-pin packages and provide four functions:

- 1) A Reset output during power-up, power-down and brownout conditions.
- 2) Battery backup switching for CMOS RAM, CMOS microprocessor or other low power logic.
- 3) A Reset pulse if the optional watchdog timer has not been toggled within a specified time.
- 4) A 1.3V threshold detector for power fail warning, low battery detection, or to monitor a power supply other than +5V.

The MAX691, MAX693 and MAX695 are supplied in 16-pin packages and perform all MAX690/692/694 functions, plus:

- 1) Write protection of CMOS RAM or EEPROM.
- 2) Adjustable reset and watchdog timeout periods.
- 3) Separate outputs for indicating a watchdog timeout, backup-battery switchover, and low Vcc.

II. Manufacturing Information

A. Description/Function:	Microprocessor Supervisory Circuits
B. Process:	M6
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	16-pin CDIP
B. Lead Frame:	Alloy42
C. Lead Finish:	63Sn/37Pb
D. Die Attach:	Agglass
E. Bondwire:	Al (1.25 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0701-0375
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	100°C/W
K. Single Layer Theta Jc:	14°C/W
L. Multi Layer Theta Ja:	N/A
M. Multi Layer Theta Jc:	N/A

IV. Die Information

A. Dimensions:	86X122 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/1.0%Si
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.9 \times 10^{-9}$$

$$\lambda = 22.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the M6 Process results in a FIT Rate of 0.22 @ 25C and 3.83 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot BPYCCZ004B, D/C 9439)

The PS77-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-100mA.

Table 1
Reliability Evaluation Test Results

MAX695MJE

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0	LPYEDA311G, D/C 0832

Note 1: Life Test Data may represent plastic DIP qualification lots.